

## VERSION SHOWING AMENDMENTS TO THE CLAIMS

This listing replaces all prior listings of the claims.

### IN THE CLAIMS

Amend the claims as follows:

1 (Currently amended). A method for patterning an unpatterned organic layer comprising a layer-forming substance (3; 13), for use in particular of organic circuits, characterized by the method comprising:

- ~~pressing~~ applying a patterning device means (2; 12) at a predetermined, elevated temperature and at a predetermined pressure to into contact points on the organic layer (3; 13), ~~the patterning means making contact with the organic layer (3; 13), the layer-forming substance of the organic layer retreating from the contact points~~ in response to the applied pressure and elevated temperature to thereby form depressions and/or holes in the organic layer but not piercing it, and the organic layer (3; 13) being permanently patterned and pierced after the pressing on.

2 (Currently amended). The method as claimed in claim 1, ~~characterized in~~ that including choosing a the substance is chosen which forms the organic layer (3; 13) in such a way that the organic layer (3; 13) is opened permanently under the applying action of the patterning device means (2; 12).

3 (Currently amended). The method as claimed in claim 1 including effecting one of the

~~preceding claims, characterized in that the applying step pressing-in is effected over a predetermined time period.~~

4 (Currently amended). The method as claimed in claim 1 ~~one of the preceding claims, characterized including supporting in that the patterning means (2;12) are device arranged on a planar carrier (1; 10, 11)~~

5 (Currently amended). The method as claimed in claim 1 ~~including forming one of the preceding claims, characterized in that the patterned organic layer (3; 13) has depressions and/or holes (6; 16) in accordance with a pattern on the patterning device means (2; 12).~~

6 (Currently amended). The method as claimed in claim 5, ~~characterized in that including providing a further layer (4) is provided, which is covered by the organic layer (3; 13), the depressions and/or holes (6; 16) essentially extending continuously to as far as the further layer (4).~~

7 (Currently amended). The method as claimed in claim 5 or 6, ~~characterized in that wherein the including forming the depressions and/or holes (6; 16) are suitable for forming plated-through holes.~~

8 (Currently amended). A device for patterning an organic layers, ~~in particular of comprising a layer-forming substance for use in an organic circuits, the device comprising:~~ characterized by patterning means (2; ~~12~~)

a support; and

a patterning arrangement coupled to the support and having predetermined dimensions, the patterning arrangement means, being arranged for being heated to at a predetermined[[,]] elevated temperature and for receiving at a predetermined pressure[[,]]for contacting after making contact with the layer-forming substance of the organic layer at the elevated temperature and predetermined pressure (3; 13), patterning the latter permanently because the organic layer (3; 13), after contact has been made, retreats at the contact points in such a way that to displace the layer-forming substance such that depressions and/or holes are formed in the layer-forming substance, which depressions and/or holes essentially correspond to the dimensions of the patterning arrangement arise there.

9 (Currently amended). The device as claimed in claim 8 wherein, characterized in that a the layer-forming substance is chosen which forms the organic layer (3; 13) in such a way that the organic layer (3; 13) is opened permanently under the action of the patterning arrangement means (2; 12).

10 (Currently amended). The device as claimed in claim 8 ~~or claim 9~~, characterized in that wherein the patterning support comprises means are arranged on a planar carrier (4).

11 (Currently amended). The device as claimed in claim 8 ~~or claim 9~~, characterized in that wherein the support is patterning means are arranged on a planar, flexible carrier (11), which is in turn arranged circumferentially on a roll-type carrier (10).

12 (Currently amended). The device as claimed in claim 11 wherein the roll-type carrier has a circumferential speed, the device including, characterized by a conveying device (18) adapted for conveying the organic layer essentially synchronously with the a circumferential speed of the roll-type carrier (10).

13 (Currently amended). The device as claimed in claim 8 ~~one of the preceding claims 8 to 13~~, characterized by including a further device (18) adapted for pressing the patterning arrangement means into the organic layer at the predetermined pressure.

14 (Currently amended). The device as claimed in claim 8 ~~one of the preceding claims 8 to 13~~, characterized by including a further device (17) adapted for heating the patterning arrangement means to the predetermined temperature.